PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT3930037

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
YANG IL KIM	06/21/2016
CHAN MOO PARK	06/21/2016
TAE GON KANG	06/21/2016
JONG CHEOL LIM	06/21/2016
YOO JIN JUNG	06/21/2016
SANG HYUN HONG	06/21/2016

RECEIVING PARTY DATA

Name:	SAMSUNG SDI CO., LTD.
Street Address:	150-20 GONGSE-RO, GIHEUNG-GU
Internal Address:	YONGIN-SI, GYEONGGI-DO
City:	YONGIN-SI
State/Country:	KOREA, REPUBLIC OF
Postal Code:	17084

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	15107210

CORRESPONDENCE DATA

Fax Number: (704)945-6735

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

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ATTORNEY DOCKET NUMBER:	1224.244
NAME OF SUBMITTER:	MELISSA B. PENDLETON
SIGNATURE:	/Melissa B. Pendleton/
DATE SIGNED:	06/22/2016

Total Attachments: 5

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Form PTO-1595 (Rev. 08/05)
OMB No. 0651-0027 (exp. 6/30/2008)

U.S. DEPARTMENT OF COMMERCE
United States Patent and Trademark Office

RECORDATION FORM COVER SHEET
PATENTS ONLY

To the Director of the U.S. Patent and Trademark Office: Please record the attached documents or the new address(es) below.

1. Name of conveying party(ies)

YANG IL KIM
CHAN MOO PARK
TAE GON KANG
JONG CHEOL LIM
YOO JIN JUNG
SANG HYUN HONG

Additional name(s) of conveying party(ies) attached? ☐ Yes ☒ No

2. Name and address of receiving party(ies)

Name: Samsung SDI Co., Ltd.
Internal Address:
Street Address: 150-20, Gongse-ro, Giheung-gu
City: Yongin-si
State: Gyeonggi-do
Country: South Korea Zip:

Additional name(s) & address(es) attached? ☐ Yes ☒ No

3. Nature of conveyance/Execution Date(s):

Execution Date(s) June 21, 2016

☒ Assignment ☐ Merger
☐ Security Agreement ☐ Change of Name
☐ Joint Research Agreement
☐ Government Interest Assignment
☐ Executive Order 9424, Confirmatory License
☐ Other

4. Application or patent number(s): ☐ This document is being filed together with a new application.

A. Patent Application No.(s)
15/107,210

B. Patent No.(s)

Additional numbers attached? ☐ Yes ☒ No

5. Name and address to whom correspondence concerning document should be mailed:

Name: Additon, Higgins & Pendleton, P.A.
Internal Address:
Street Address: 10706 Sikes Place
Suite 350
City: Charlotte
State: NC Zip: 28277-8202
Phone Number: 704-945-6700
Fax Number: 704-945-6735
Email Address:

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 1.21(h) & 3.41) $

☐ Authorized to be charged by credit card
☐ Authorized to be charged to deposit account
☐ Enclosed
☐ None required (government interest not affecting title)

8. Payment Information

a. Credit Card Last 4 Numbers
Expiration Date
b. Deposit Account Number
Authorized User Name

9. Signature: /Melissa B. Pendleton/
Signature

June 22, 2016
Date

Melissa B. Pendleton
Name of Person Signing

Total number of pages including cover sheet, attachments, and documents: 5

Documents to be recorded (including cover sheet) should be faxed to (571) 273-0140, or mailed to:
Mail Stop Assignment Recordation Services, Director of the USPTO, P.O.Box 1450, Alexandria, V.A. 22313-1450

COMBINED DECLARATION AND ASSIGNMENT

WHEREAS, I, **Yang Il KIM**, a citizen of the Republic of Korea, with a mailing address of 56, Gosan-ro, Uiwang-si, Gyeonggi-do, Republic of Korea; **Chan Moo PARK**, a citizen of the Republic of Korea, with a mailing address of 56, Gosan-ro, Uiwang-si, Gyeonggi-do, Republic of Korea; **Tae Gon KANG**, a citizen of the Republic of Korea, with a mailing address of 56, Gosan-ro, Uiwang-si, Gyeonggi-do, Republic of Korea; **Jong Cheol LIM**, a citizen of the Republic of Korea, with a mailing address of 56, Gosan-ro, Uiwang-si, Gyeonggi-do, Republic of Korea; **Yoo Jin JUNG**, a citizen of the Republic of Korea, with a mailing address of 56, Gosan-ro, Uiwang-si, Gyeonggi-do, Republic of Korea; and **Sang Hyun HONG**, a citizen of the Republic of Korea, with a mailing address of 56, Gosan-ro, Uiwang-si, Gyeonggi-do, Republic of Korea (hereinafter referred to as "ASSIGNOR"), am a joint inventor of certain new and useful improvements (hereinafter collectively referred to as "INVENTION") in *Thermoplastic Resin Composition Having Excellent Shock Resistance and Light Resistance*, for which an application for United States Letters Patent is being filed concurrently herewith and which application claims priority from an International Application filed on June 10, 2014, under Serial No. PCT/KR2014/005080, and a Korean application filed on December 30, 2013, under Serial No. 10-2013-0167879, all applications listed above being hereinafter referred to as the "APPLICATION"; and

WHEREAS, Samsung SDI Co., Ltd., a corporation of the Republic of Korea (hereinafter referred to as "ASSIGNEE"), having a principal place of business at 150-20, Gongse-ro, Giheung-gu, Yongin-si, Gyeonggi-do, Republic of Korea, has acquired the equitable right, title, and interest—and is desirous of acquiring any remaining right, title, and interest—in and to said INVENTION as described in said APPLICATION, and in and to any and all Letters Patent that shall be granted with respect to said INVENTION in the United States of America and all foreign countries;

NOW, THEREFORE, be it known that for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, I, the ASSIGNOR, have sold, assigned, transferred, and conveyed unto said ASSIGNEE, its successors and assigns, my equitable right, title, and interest—and by these presents do hereby sell, assign, transfer, and convey unto said ASSIGNEE, its successors and assigns any remaining right, title, and interest—in and to said INVENTION and APPLICATION, in and to any and all continuations, continuations-in-part, or divisions thereof, and in and to any and all Letters Patent of the United States of America and all foreign countries or reissues, reexaminations, or extensions thereof that may be granted therefore or thereon, for the full term for which said Letters Patent may be granted, together with the right to claim the priority of said APPLICATION in all foreign countries in accordance with international treaties and conventions, the same to be held and enjoyed by said ASSIGNEE, its successors and assigns, as fully and entirely as the same would have been held and enjoyed by me if an assignment and sale had not been made.

I acknowledge that at the time the INVENTION was made, the INVENTION was subject to an obligation of assignment to said ASSIGNEE. I further acknowledge that said ASSIGNEE has the sole right to determine patent prosecution strategies with respect to said INVENTION and all corresponding applications, and hereby request that Letters Patent be issued in accordance with this assignment.

I further covenant and agree to bind my heirs, legal representatives, and assigns, promptly to communicate to said ASSIGNEE or its representatives any facts known to me relating to said INVENTION, to testify in any interference or legal proceedings involving said INVENTION, to execute any additional papers that may be requested to confirm the right of the ASSIGNEE, its representatives, successors or assigns to secure patent or similar protection for said INVENTION in all countries and to vest in the ASSIGNEE complete title to said INVENTION and Letters Patent, without further compensation, but at the expense of said ASSIGNEE, its successors, assigns and other legal representatives.

As the below named inventor, I hereby declare:

The application for United States Letters Patent being filed concurrently herewith was made or authorized to be made by me.

I believe that I am the original or an original joint inventor of a claimed invention in the application.

I hereby acknowledge that any willful false statement made in the declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

IN WITNESS WHEREOF, I have hereunto signed my name on the day and year set forth below.

June 21, 2016 Yang il KIM
Yang Il KIM

June 21, 2016 박찬무
Chan Moo PARK

June 21, 2016 Tae Gon Kang
Tae Gon KANG

June 21, 2016 임종철
Jong Cheol LIM

June 21, 2016 Yoo Jin Jung

Yoo Jin JUNG

June 21, 2016 Sang Hyun Hong

Sang Hyun HONG